Temperature) of the epoxy package 8, there is a thermal shrinkage stress imposing on the interface of the epoxy package 8, the shoulder 12 and the solder platform 17 (Referring to Fig. 10). As a result, a complete sealing (Referring to complete seal interface 24) is formed along the interface of the epoxy package 8, the shoulder 12 and solder platform 17. Again, any would-be gap is totally eliminated. Since the present invention can create complete seal interface 23 and 24 to avoid the generation of the moisture gap so as to improve the ability of the die 16 against the moisture and to extend the lifetime of the die 16.

Please replace the Abstract beginning at page 10, line 1 with the following amended Abstract:

Abstract

The invention related to a diode 2 comprising a connecting means (6) and a heat sink base (7). Said connecting (6) has a flat end (5) fixed on a die 16 and another end without fix shape. Said heat sink base (7) comprises: a base (18) which is at the bottom of said heat sink base (7); a press-fit region (4) which is set around said base (18); a solder platform (17) which is set above said base (18) and has an anchor mechanism (11) equipped with a shoulder (12) and a kink (13); a die (16) which has a first side and a second side electrically coupled to said flat-end (5) and said solder platform (17), respectively, and is fixed on said solder platform (17); [[a]] the shoulder (12) which is extended acclivitously from said solder platform (17), the root of said shoulder connected to said solder platform 17 ~~having a~~ via the kink (13); and a cup (14) which is extended upwardly from the periphery of said base (18).